5   <u>Abstract</u>

The present invention is directed to low density modeling compounds which comprise little or no water and which overcome or at least substantially reduce problems associated with existing modeling compounds and modeling

10   doughs. The preferred exemplary embodiment of the present invention comprises polyvinyl chloride resin, primary plasticizer, secondary plasticizer, stabilizer, microspheres, and a thixotropic agent. The modeling compound of the present invention comprises .3% or less water by weight of the compound.

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